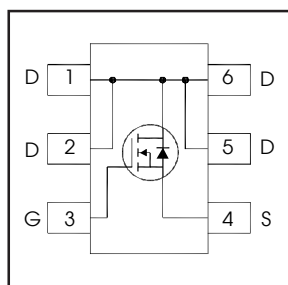


IRLTS6342PbF

HEXFET® Power MOSFET

V_{DS}	30	V
V_{GS}	±12	V
$R_{DS(on) \text{ max}}$ (@ $V_{GS} = 4.5V$)	17.5	mΩ
$R_{DS(on) \text{ max}}$ (@ $V_{GS} = 2.5V$)	22.0	mΩ
Q_g (typical)	11	nC
I_D (@ $T_A = 25^\circ C$)	8.3	A



Applications

- System/Load Switch

Features and Benefits

Features

Industry-Standard TSOP-6 Package
RoHS Compliant Containing no Lead, no Bromide and no Halogen
MSL1, Consumer Qualification

⇒

Resulting Benefits

Multi-Vendor Compatibility
Environmentally Friendlier
Increased Reliability

Orderable part number	Package Type	Standard Pack		Note
		Form	Quantity	
IRLTS6342TRPBF	TSOP-6	Tape and Reel	3000	

Absolute Maximum Ratings

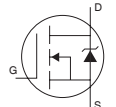
	Parameter	Max.	Units
V_{DS}	Drain-to-Source Voltage	30	V
V_{GS}	Gate-to-Source Voltage	±12	
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 4.5V$	8.3	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ 4.5V$	6.7	
I_{DM}	Pulsed Drain Current ①	64	
$P_D @ T_A = 25^\circ C$	Power Dissipation ③	2.0	W
$P_D @ T_A = 70^\circ C$	Power Dissipation ③	1.3	
	Linear Derating Factor	0.02	W/°C
T_J	Operating Junction and	-55 to + 150	°C
T_{STG}	Storage Temperature Range		

Notes ① through ④ are on page 2

Static @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
BV_{DSS}	Drain-to-Source Breakdown Voltage	30	—	—	V	$V_{GS} = 0V, I_D = 250\mu A$
$\Delta BV_{DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	23	—	mV/ $^\circ\text{C}$	Reference to $25^\circ\text{C}, I_D = 1\text{mA}$
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	14.0	17.5	m Ω	$V_{GS} = 4.5V, I_D = 8.3A$ ②
		—	17.5	22.0		$V_{GS} = 2.5V, I_D = 6.7A$ ②
$V_{GS(th)}$	Gate Threshold Voltage	0.5	—	1.1	V	$V_{DS} = V_{GS}, I_D = 10\mu A$
$\Delta V_{GS(th)}$	Gate Threshold Voltage Coefficient	—	-4.3	—	mV/ $^\circ\text{C}$	
I_{DSS}	Drain-to-Source Leakage Current	—	—	1.0	μA	$V_{DS} = 24V, V_{GS} = 0V$
		—	—	150		$V_{DS} = 24V, V_{GS} = 0V, T_J = 125^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{GS} = 12V$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{GS} = -12V$
g_{fs}	Forward Transconductance	25	—	—	S	$V_{DS} = 10V, I_D = 6.4A$
Q_g	Total Gate Charge	—	11	—	nC	$V_{GS} = 4.5V$
Q_{gs}	Gate-to-Source Charge	—	0.5	—		$V_{DS} = 15V$
Q_{gd}	Gate-to-Drain Charge	—	4.6	—		$I_D = 6.4A$
R_G	Gate Resistance	—	2.2	—	Ω	
$t_{d(on)}$	Turn-On Delay Time	—	5.4	—	ns	$V_{DD} = 15V, V_{GS} = 4.5V$ ③ $I_D = 6.4A$ $R_G = 6.8\Omega$ See Figs. 18
t_r	Rise Time	—	11	—		
$t_{d(off)}$	Turn-Off Delay Time	—	32	—		
t_f	Fall Time	—	15	—		
C_{iss}	Input Capacitance	—	1010	—	pF	$V_{GS} = 0V$
C_{oss}	Output Capacitance	—	96	—		$V_{DS} = 25V$
C_{rss}	Reverse Transfer Capacitance	—	70	—		$f = 1.0\text{MHz}$

Diode Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	2.0	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I_{SM}	Pulsed Source Current (Body Diode) ①	—	—	64		
V_{SD}	Diode Forward Voltage	—	—	1.2	V	$T_J = 25^\circ\text{C}, I_S = 8.3A, V_{GS} = 0V$ ②
t_{rr}	Reverse Recovery Time	—	13	20	ns	$T_J = 25^\circ\text{C}, I_F = 6.4A, V_{DD} = 24V$ $di/dt = 100/\mu s$ ②
Q_{rr}	Reverse Recovery Charge	—	5.8	8.7	nC	

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JA}$	Junction-to-Ambient ③	—	62.5	$^\circ\text{C/W}$

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Pulse width $\leq 400\mu s$; duty cycle $\leq 2\%$.
- ③ When mounted on 1 inch square copper board.
- ④ R_θ is measured at T_J of approximately 90°C .

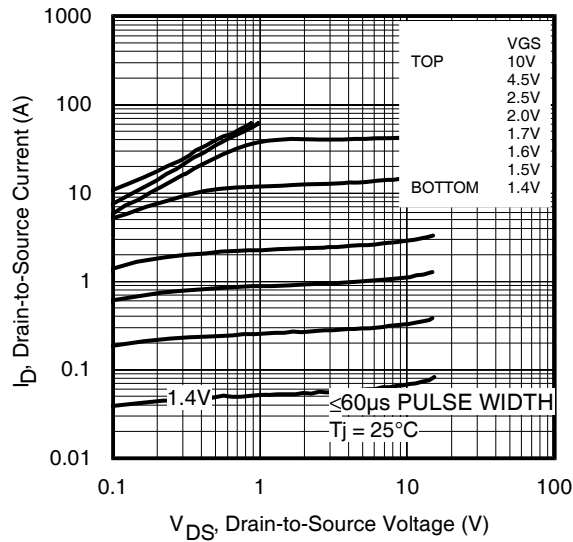


Fig 1. Typical Output Characteristics

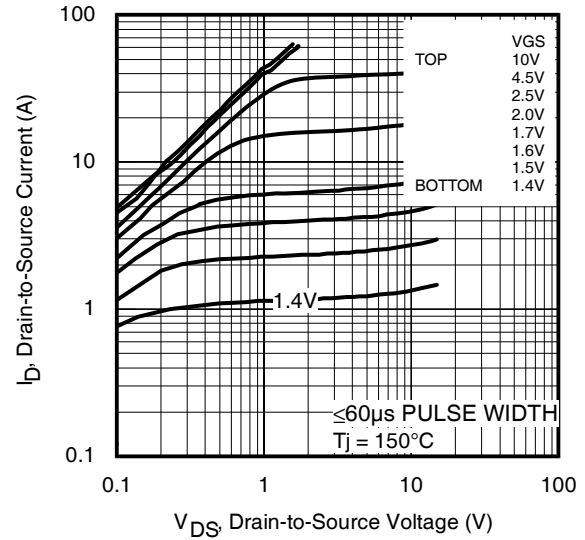


Fig 2. Typical Output Characteristics

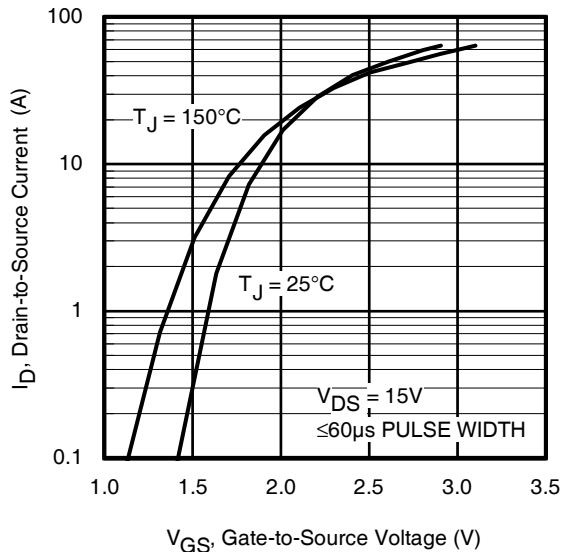


Fig 3. Typical Transfer Characteristics

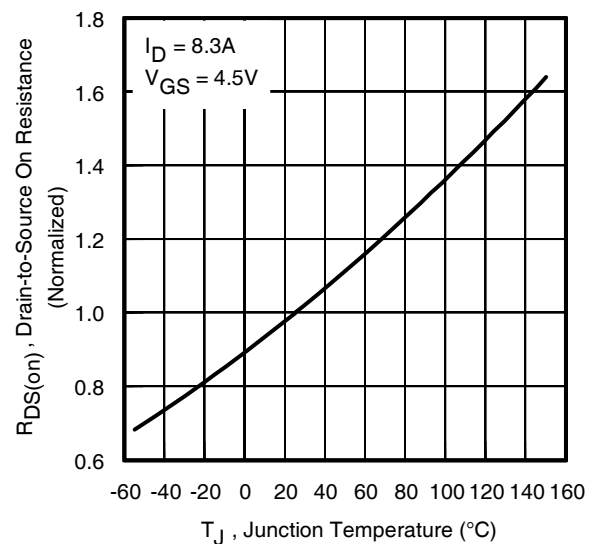


Fig 4. Normalized On-Resistance vs. Temperature

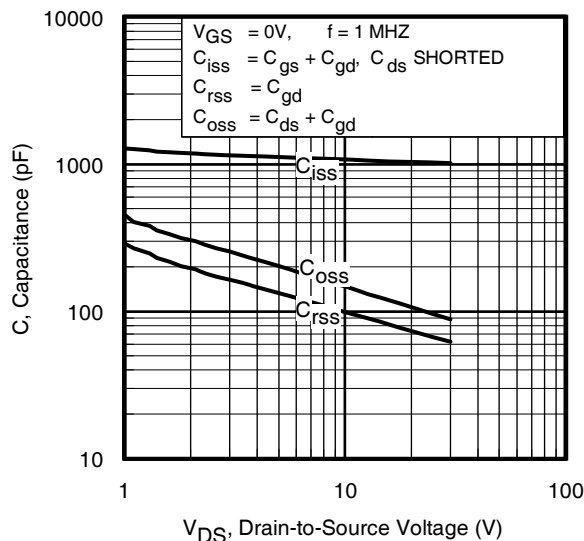


Fig 5. Typical Capacitance vs. Drain-to-Source Voltage
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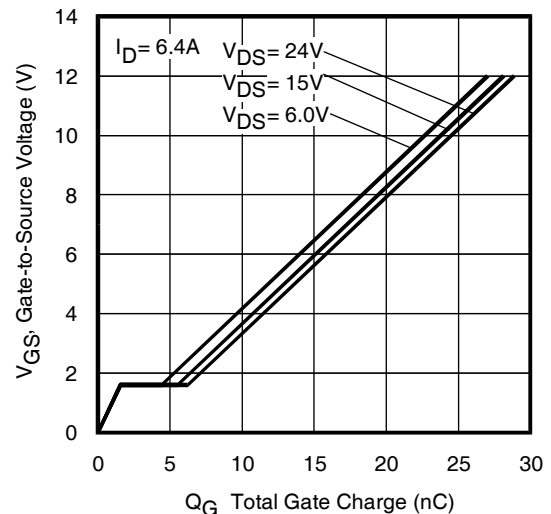


Fig 6. Typical Gate Charge vs. Gate-to-Source Voltage

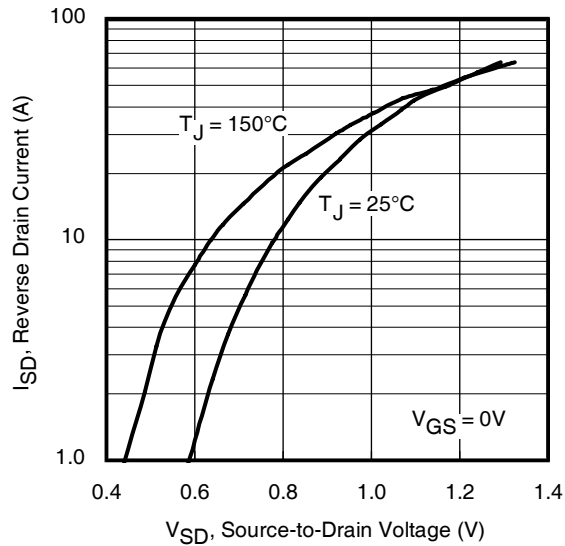


Fig 7. Typical Source-Drain Diode Forward Voltage

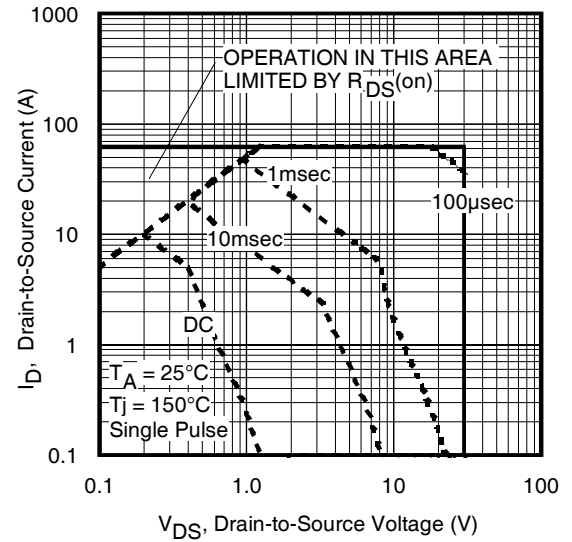


Fig 8. Maximum Safe Operating Area

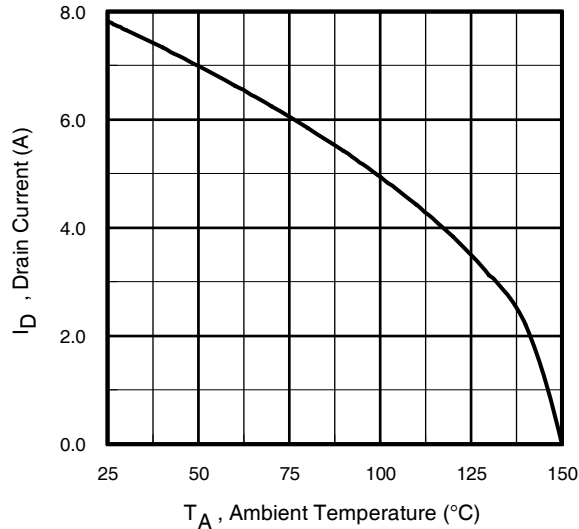


Fig 9. Maximum Drain Current vs. Ambient Temperature

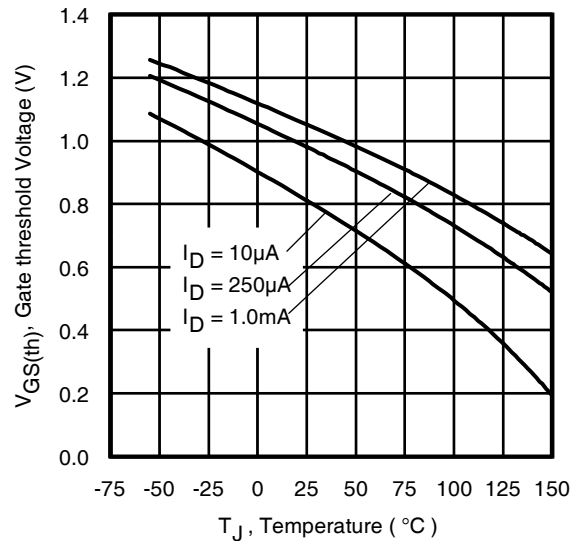


Fig 10. Threshold Voltage vs. Temperature

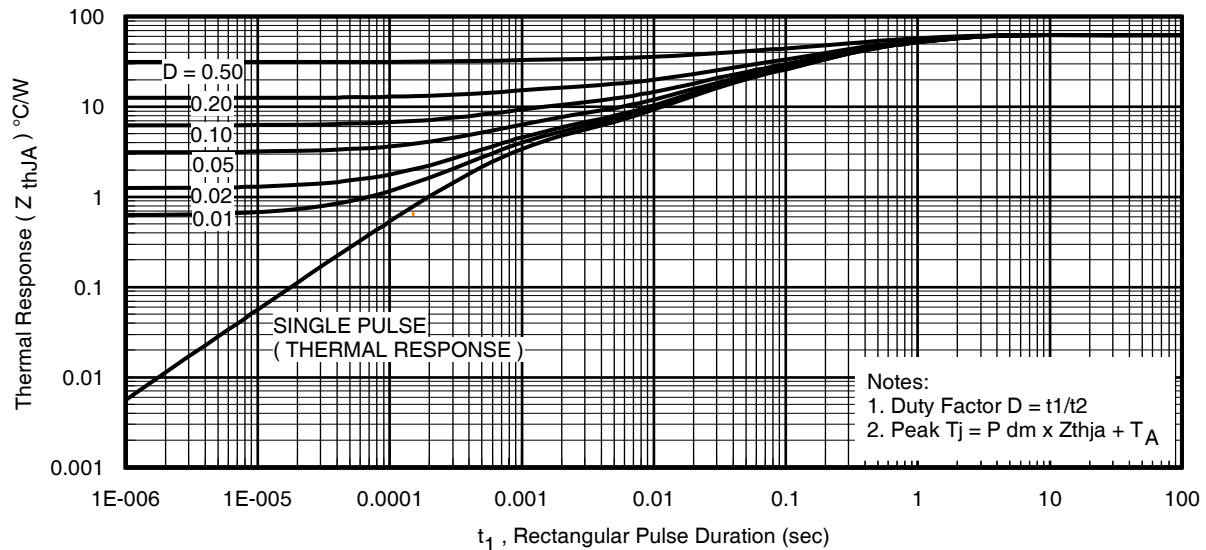


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

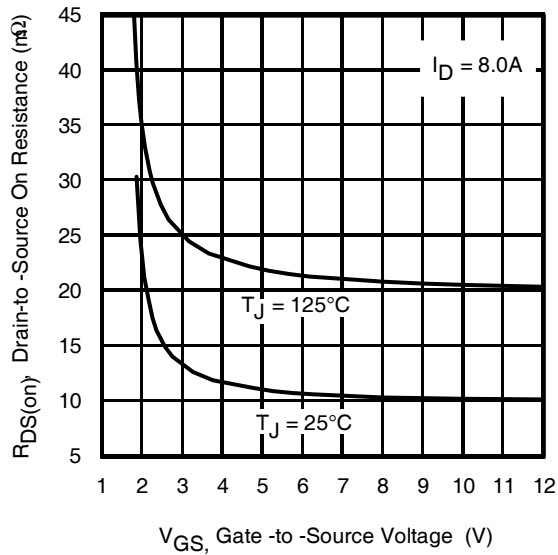


Fig 12. On-Resistance vs. Gate Voltage

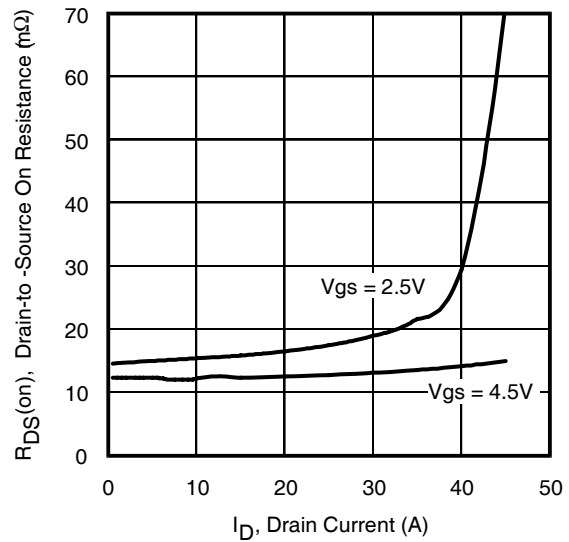


Fig 13. Typical On-Resistance vs. Drain Current

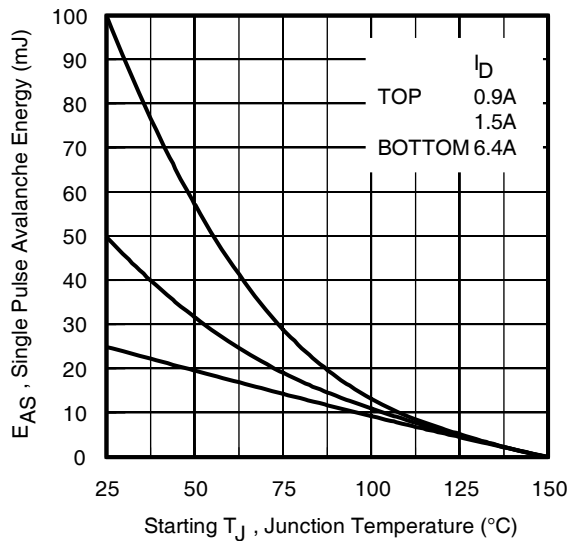


Fig 14. Maximum Avalanche Energy vs. Drain Current

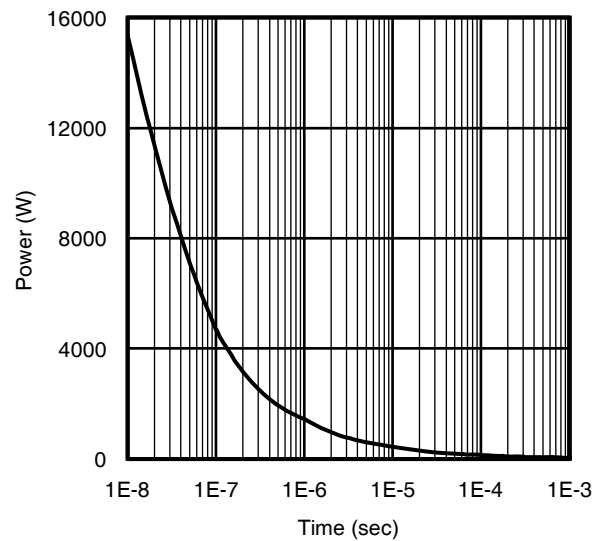
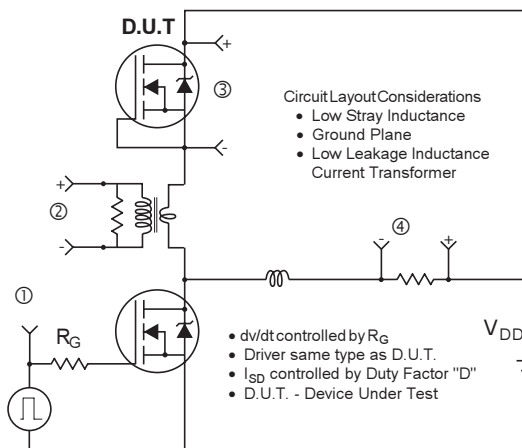
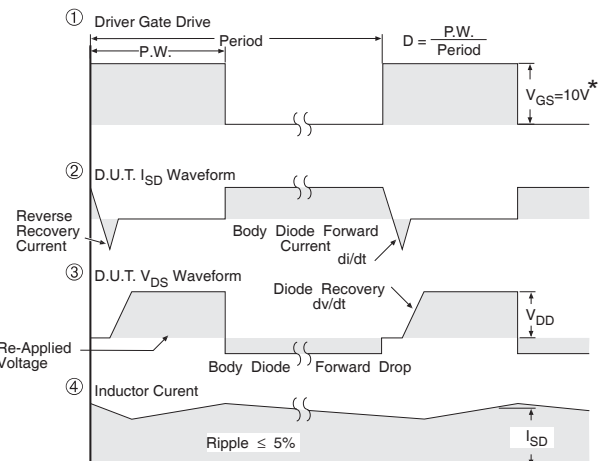


Fig 15. Typical Power vs. Time



* $V_{GS} = 5V$ for Logic Level Devices

Fig 16. Peak Diode Recovery dv/dt Test Circuit for N-Channel HEXFET® Power MOSFETs

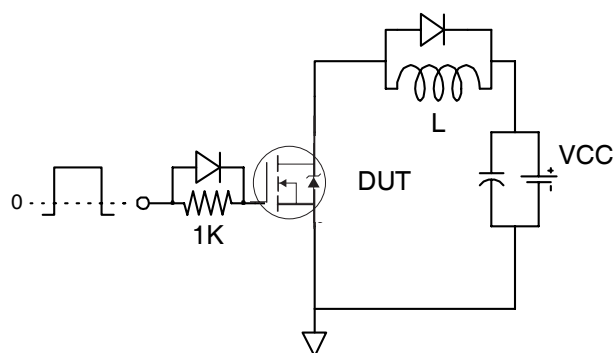


Fig 17a. Gate Charge Test Circuit

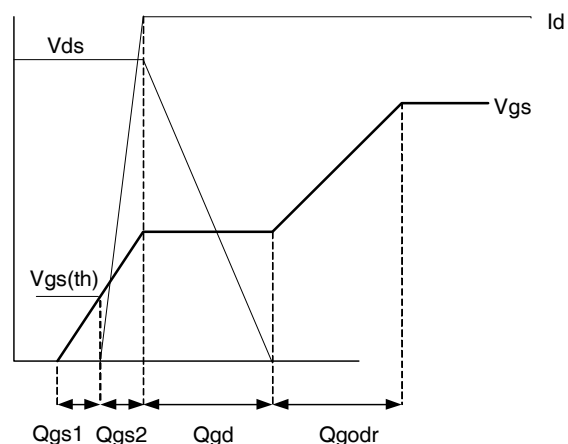


Fig 17b. Gate Charge Waveform

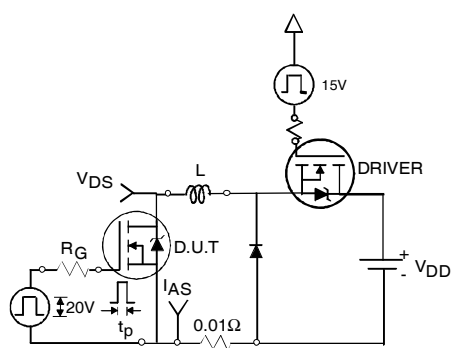


Fig 18a. Unclamped Inductive Test Circuit

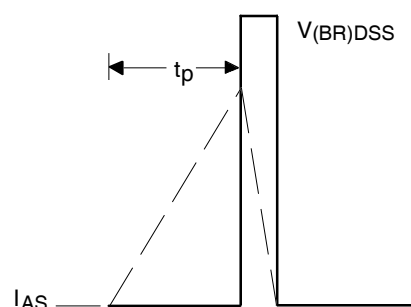


Fig 18b. Unclamped Inductive Waveforms

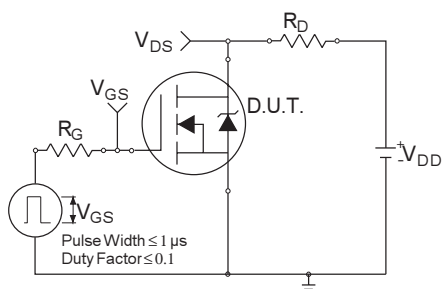


Fig 19a. Switching Time Test Circuit

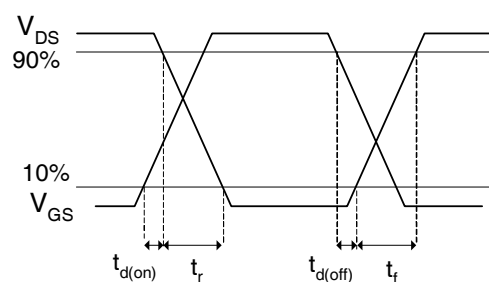


Fig 19b. Switching Time Waveforms

Technical drawing of a mechanical part showing two views: a top view and a side view.

Top View Dimensions:

- Overall width: 3.00 (.118)
- Overall height: 3.00 (.118)
- Distance from top edge to center of top row of holes: 2.80 (.111)
- Distance from bottom edge to center of bottom row of holes: 2.60 (.103)
- Distance between centers of holes in a row: 0.50 (.019)
- Hole diameter: 0.15 (.006)
- Surface finish symbol: 0.15 (.006) (M) C A (S) B (S)

Side View Dimensions:

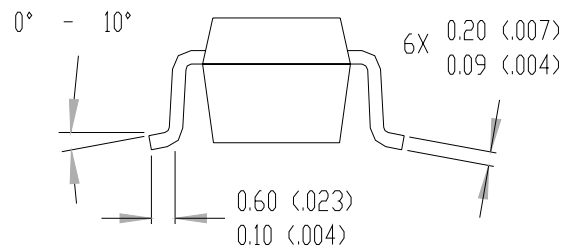
- Overall height: 1.30 (.051)
- Distance from top edge to center of holes: 1.45 (.057)
- Distance from bottom edge to center of holes: 0.90 (.036)
- Base thickness: 0.15 (.006)
- Surface finish symbol: 0.10 (.004)

Other Features:

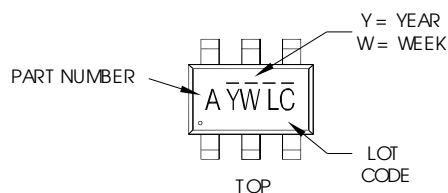
- Top view shows six holes arranged in two rows of three.
- Side view shows a profile with a maximum height of 1.30 (.051).
- Surface finish symbols are present on several surfaces.

A 3x3 grid with letters and numbers. The top row contains 'D', 'D', 'S'. The middle row contains '6', '5', '4'. The bottom row contains '.1', '2', '3'. Below the grid, there are three columns of two boxes each, labeled 'D', 'D', 'G' from left to right.

1. DIMENSIONING & TOLERANCING PER ANSI Y14.5M-1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).



W = (1-26) IF PRECEDED BY LAST DIGIT OF CALENDAR YEAR



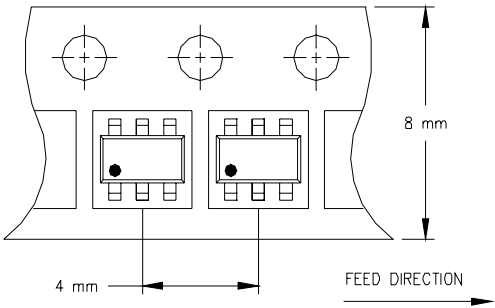
A = SI3443DV	O = IRLTS6342TRPBF
B = IRF5800	P = IRFTS8342TRPBF
C = IRF5850	R = IRFTS9342TRPBF
D = IRF5851	S = IRLTS2242TRPBF
E = IRF5852	
F = IRF5801	
G = IRF5803	
H = IRF5804	
I = IRF5805	
J = IRF5806	
K = IRF5810	
N = IRF5802	

YEAR	Y	WORK WEEK	W
2001	1	01	A
2002	2	02	B
2003	3	03	C
2004	4	04	D
2005	5		
2006	6		
2007	7		
2008	8		
2009	9		
2010	0	24	X
		25	Y
		26	Z

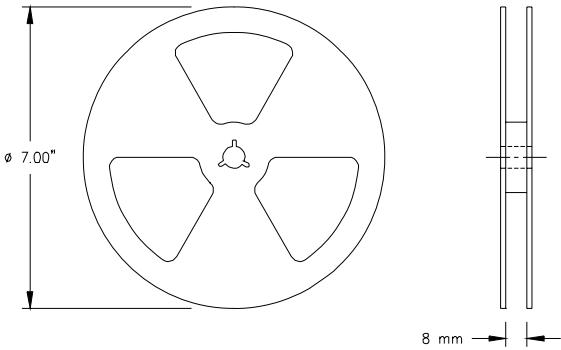
YEAR	Y	WORK WEEK	W
2001	A	27	A
2002	B	28	B
2003	C	29	C
2004	D	30	D
2005	E		
2006	F		
2007	G		
2008	H		
2009	J		
2010	K	50	X
		51	Y
		52	Z

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TSOP-6 Tape & Reel Information



NOTES:
1. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES:
1. OUTLINE CONFORMS TO EIA-481 & EIA-541.

Qualification information[†]

Qualification level	Consumer ^{††} (per JEDEC JESD47F ^{†††} guidelines)	
Moisture Sensitivity Level	TSOP-6	MSL 1 (per JEDEC J-STD-020D ^{†††})
RoHS compliant	Yes	

[†] Qualification standards can be found at International Rectifier's web site
<http://www.irf.com/product-info/reliability>

^{††} Higher qualification ratings may be available should the user have such requirements.
Please contact your International Rectifier sales representative for further information:
<http://www.irf.com/whoto-call/salesrep/>

^{†††} Applicable version of JEDEC standard at the time of product release.

Data and specifications subject to change without notice.

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IR Rectifier

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